UltraSIM

The ultrathin gold solution for low-end SIM cards

The Gold nano-protection layer of Linxens UltraSIM delivers the thinnest gold configuration available in 2FF and 3FF. UltraSIM offers cost-efficient solution without compromising at all the product performance, maintaining scratch and corrosion resistance.

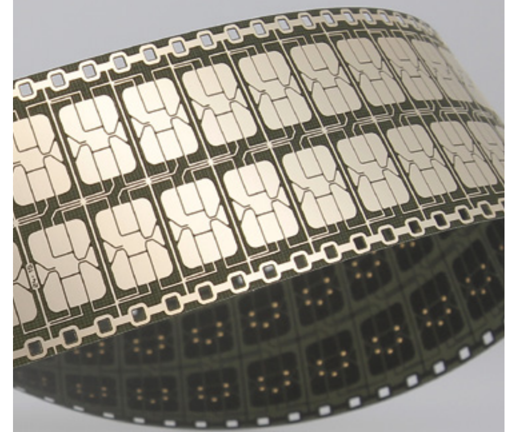
Key Features

- Nano-protection of Gold on contact surface preventing nickel oxidation and allergies
- Visual appearance on contact surface remains yellowish
- Basic corrosion resistance

Typical Product Designs

Solution	Part Number	Modules	Chip Dimension	Cavity
2FF / 3FF	9X12415	6	3.2 x 3 mm	No
2FF / 3FF	9X12416	6	1.8 x 1.8 mm	✓
2FF / 3FF	9X12501	6	2.6 x 2.6 mm	No
2FF / 3FF	9X13901	6	1.8 x 1.8 mm	✓
2FF / 3FF	9X13902	6	3.2 x 3 mm	No
2FF / 3FF	9X13704	6	1.8 x 1.8 mm	✓
2FF / 3FF	9X13705	6	3 x 3 mm	No
2FF / 3FF	9X21002	6	3.9 x 4.9 mm	✓
2FF / 3FF	9X21003	6	4.1 x ≤ 6 mm	No
4FF	9X13101	6	2.5 x 2.5 mm	✓
4FF	9X12420	6	1.8 x 1.8 mm	✓
4FF	9X21005	6	3.9 x 4.9 mm	✓
4FF	9X25301	6	3.1 x 3.6 mm	✓

MICROCONNECTORS



Overview

Material
- Film base: Standard Epoxy glass
- Adhesive: High temperature modified Epoxy MCHT
- Copper: ED29µ

Thickness
- Total: 159 ± 20 µm
- Plating Thickness
  - Contact side
    - Ni: 1.2 µm ± 0.3 µm
    - Au: Nano-protection
  - Back side:
    - Ni: 5 (-2 +3) µm
    - Au: 0.25 (-0.10 +0.20) µm

Plating Performance
Basic corrosion resistance

Compliance Labels
- ISO 10373
- ISO 7810

Application Area
- Telecom

Options
- Micro-Etched / Fully-Etched
- 2FF/3FF/4FF

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